



Sierra Components, Inc.

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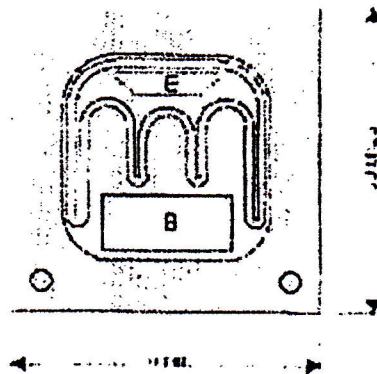
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

P/N: 2N3700

GEO: 4500

**Chip Type: 2C3700
Geometry: 4500**

**Polarity NPN
Die Size: 30x30**



Chip type 2C by Semicoa Semiconductors provides performance similar to these devices.

Product Summary:

APPLICATIONS: Designed for medium power amplifier and switching applications.

Features:

- Medium power ratings

APPROVED BY: MG

DIE SIZE : 30 x 30 Mils

DATE: 3/7/13

MFG: Semicoa

THICKNESS: N/A

P/N: 2N3700